is used substantially more intensively. That is, even those areas are used which are otherwise left free so as to prevent short-circuits to the through-connections.

The short-circuits here are not necessarily extremely low-impedance short-circuits in each case. Short-circuits are also present when the insulating resistance is less than infinite, so there is the possibility that creeping currents will flow.

A method for the production of circuit boards is known from document WO 02/078411 A, said circuit boards having points at which through-connections are created, at least in the proximity of which strip connectors or an electrically conductive layer is also provided. Here the through-bores of the through-connections have diameters which are above a size range of 20 micrometers. Additionally a method step is lacking in which the through-connecting takes place in that an electrically conductive general layer is formed before the through-holes are filled with a standard medium.

A method for the production of multilayer circuit boards is known from document US-A-5 758 413 with a diameter of 120 micrometers and less only for the through-connections.

The object of the invention is to specify a simple and low-cost method for the production of circuit boards and/or corresponding constructs comprising points at which through-connections are created and, at least in the proximity of said points, strip conductors or similar are also provided.

This object is achieved according to the invention in a method which comprises the method steps specified in claim 1.

This method has the advantage that it is easy to control and that it nonetheless ensures that no short circuits are produced between the through-connections and the strip conductors or correspondingly similar arranged at least in the proximity of the through-connections.

The method is easy to control and is low in cost because, in particular, a very complex brushing method step, in which the surface of the circuit board or of a corresponding construct is brushed, is cut out. The method is also simple and low in cost because standard media can be used throughout and consequently it is not necessary to use special media at least in some method steps. The method also guarantees short-circuit protection above the through-connections in particular because in practice three insulation layers are applied above the